

Integration of Graphene-based nanostructures for novel gaseous detectors

Giorgio Orlandini

On behalf of CERN GDD group

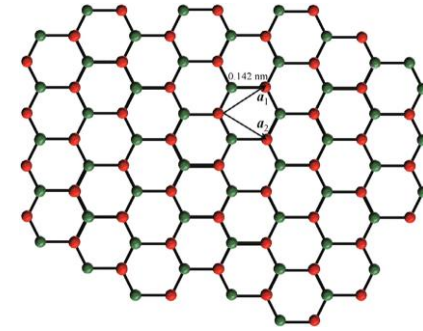
RD51 collaboration meeting 13-17 June 2022

Graphene transfer on top of GEM foils

Properties of 2D materials such as graphene could offer new perspectives for novel gaseous radiation detectors.

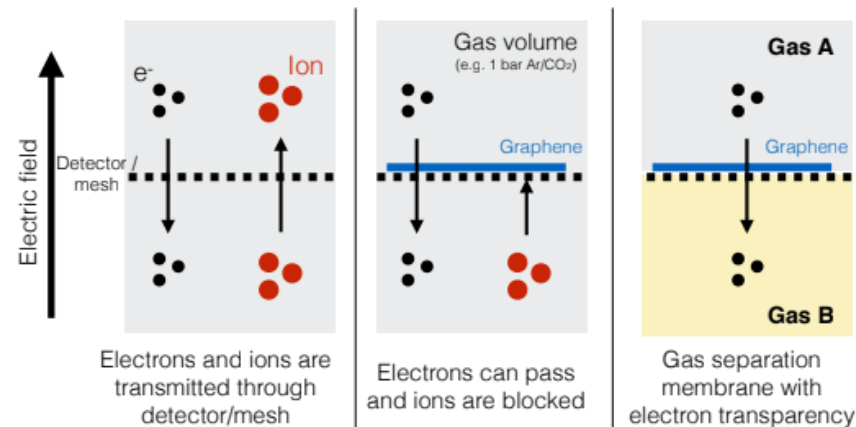
Graphene:

- **Single/few layers** of graphite
- Each layer is 1 atom thick
- **C atoms** arranged in a hexagonal lattice with sp^2 hybridised atoms(planar, 120°)
- Promising material:
- It is easy to handle \longrightarrow without the necessity of clean room facilities



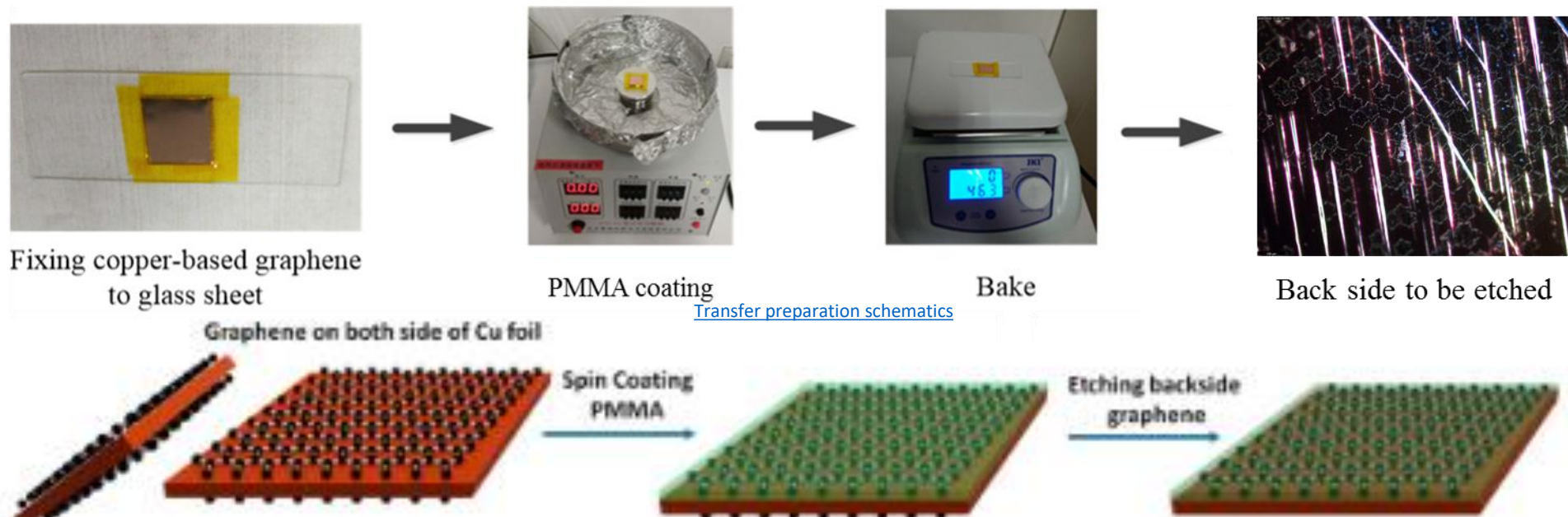
Mono/few layers of Graphene are transferred on top of GEMs foils:

- **Ions back flow** suppression \longrightarrow Graphene should be transparent to the electrons but not to ions.
- **Gas separation** Graphene should physically separate the drift and amplification regions.



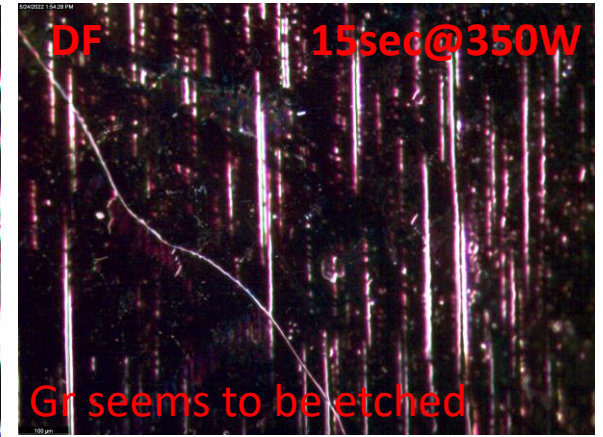
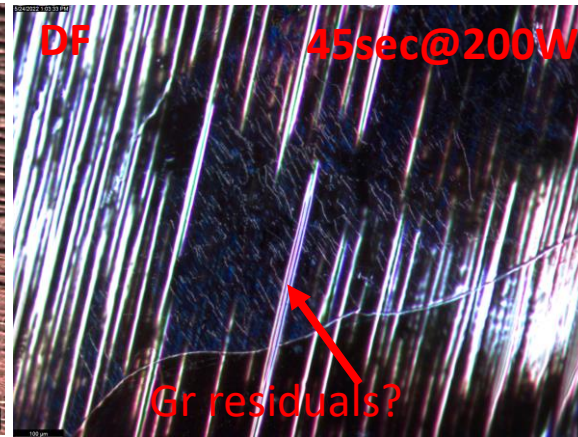
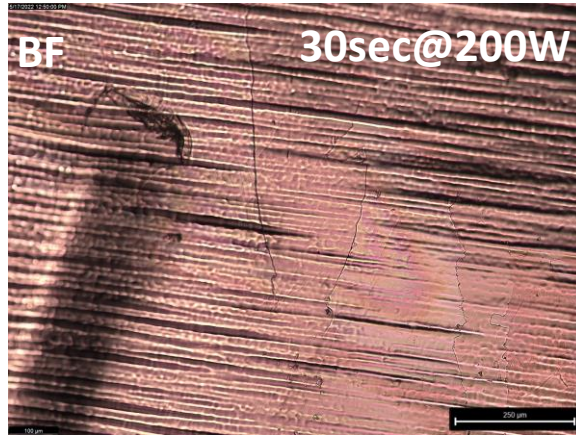
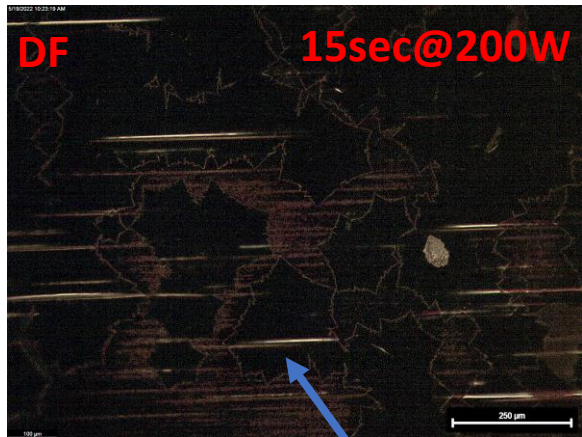
Graphene wet transfer procedure

- **Graphene foil preparation:**
- **PMMA coating:** the PMMA was spin-coated on the CVD graphene on copper foil; Then, baked @90°C for 2 min.
- **Backside Etching:** Because during CVD process grew graphene layers on both sides of the copper foil, graphene on other side (no PMMA) of the foil is etched via an **oxygen plasma** treatment.

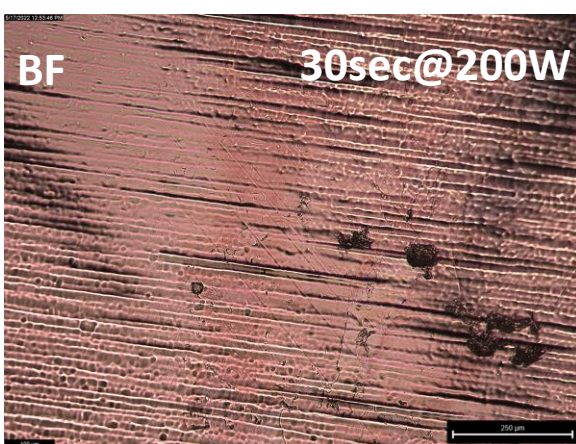


Oxygen plasma etching

Optical Microscope images showing the back side of the foils after the dry etching treatment

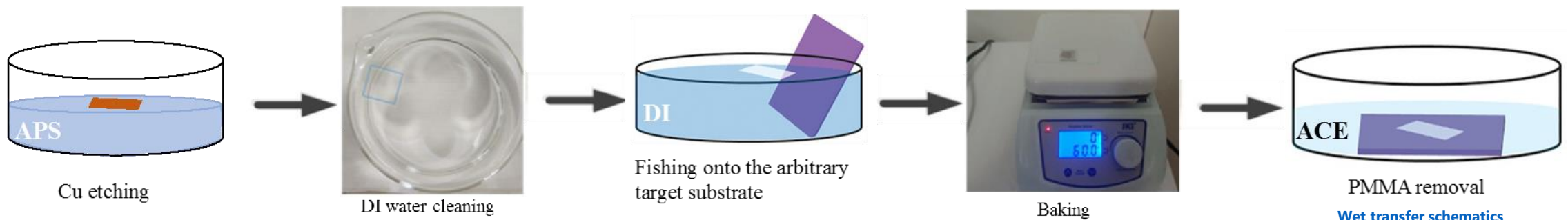


Gr residuals?



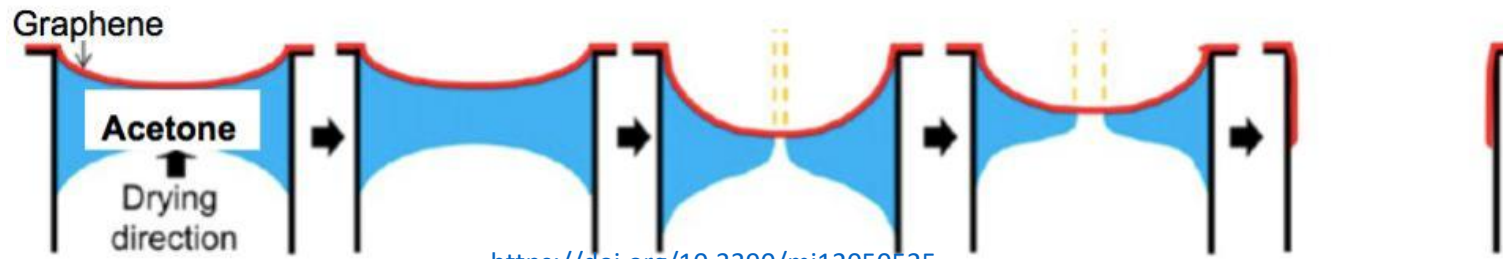
Graphene WET transfer procedure

- **Transfer procedure:**
- **Wet etching treatment:** The **copper foil is etched** in an Ammonium persulfate solution (APS) for $\sim 1.5/2$ h.
- After copper etching, PMMA/Graphene is **rinsed** with fresh deionized water.
- After the DI water rinsing, the PMMA/graphene stack is **left on the DI water for 12 h** to remove impurities and residue.
- **PMMA/graphene stack is fished** onto the target substrate.
- Substrate is backed @90°C for 20min.
- **PMMA removal:** PMMA is removed soaking the sample in **Acetone**



Free standing graphene transfer

- Critical steps of transferring a single/few layers of graphene on holes:
 - **PMMA removal and drying procedure:**
- **Adhesion issues of Graphene** during the **PMMA removal**: some areas of the layer detach from the substrate. Not optimized substrates:
 - Surface roughness
 - Coating
- **Drying procedure:** If the sample is dipped in ACE, during the drying process solvent surface tension acting on the graphene membrane will completely break the membrane.



<https://doi.org/10.3390/mi12050525>

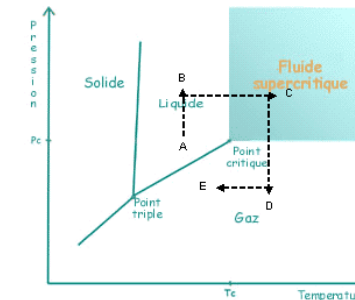
To solve the issues during the drying procedure, two approaches have been explored:

Inverted floating method (IFM)

- **PMMA** is dissolved in **ACE** via an **IFM**

Critical point dryer (CPD)

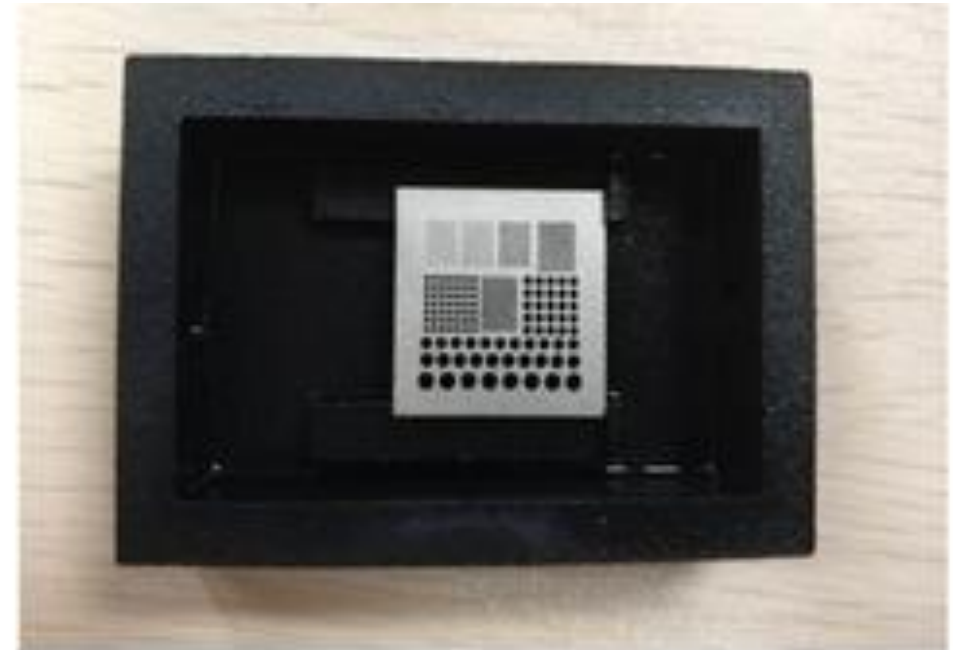
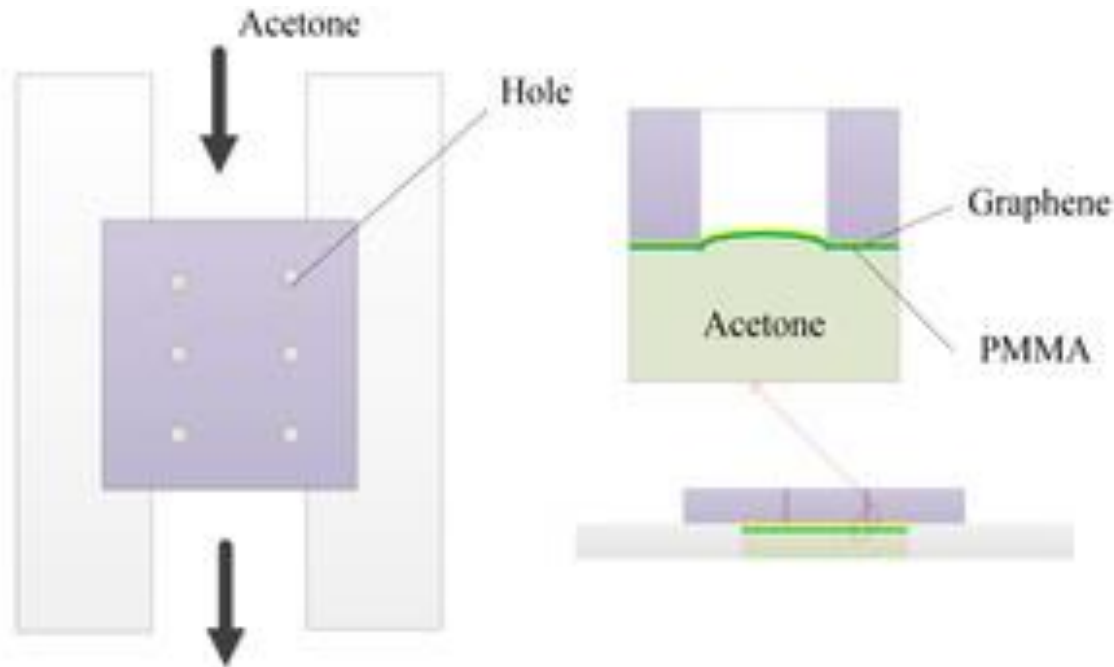
- **PMMA** dissolved by dipping the sample in **ACE**
- **Dried CPD**



[CMI critical point dryer](https://www.cmi.com/critical-point-dryer)

Inverted floated method

- PMMA removal → The sample is placed upside down in order to keep only the PMMA/Gr side in contact with the solvent.
- Few minutes in contact with the ACE and dried
- To have more gentle drying procedure, ACE could be exchanged with a solvent with a lower surface tension



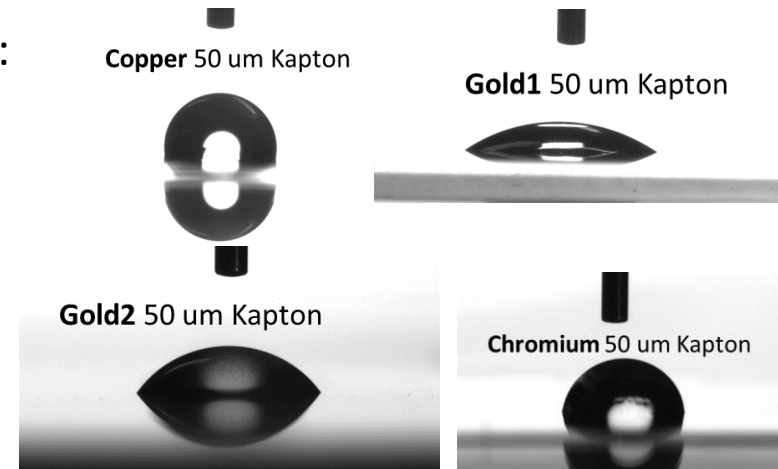
Graphene transfer on foils

- **Wet Graphene transfers** have been explored on foils with different coatings available for GEMs fabrication:

Kapton thickness	Coatings		
50 um	Cu	Au1	Cr
25 um	Cu	\	Cr

- **Contact angle measurements** on different available foils:

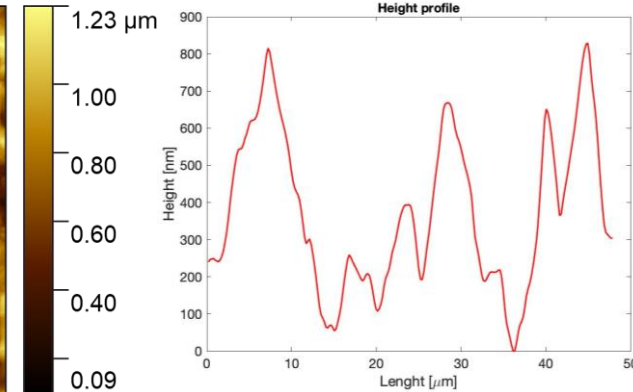
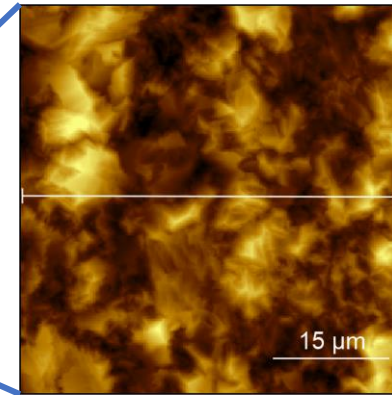
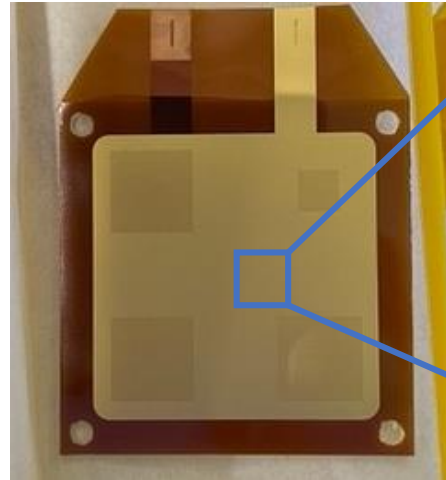
50 um Kapton thickness	
Coating type	Contact angle measurement [deg]
Copper	90.42
Gold1	39.72
Gold2	55.13
Chromium	84.32



- **Surface roughness** → In the order of few 100 nm for all the foils except for Chromium which is few nm

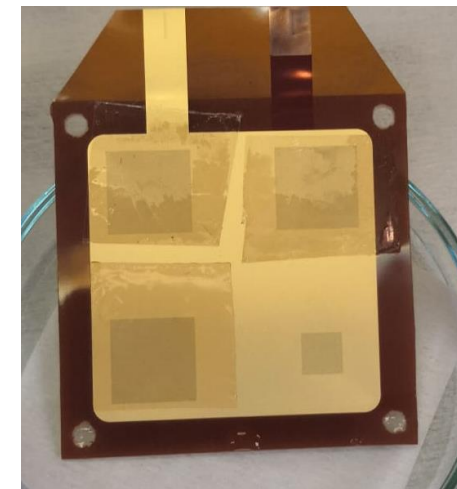
Graphene transfer on GEMs

- **Substrate details:**
- Au coated GEM
- Holes diameter: 50 μm
- Kapton Thickness: 50 μm



- **Transfer details:**
- Graphene is protected w/ PMMA+PPC coating
- Cu etching in APS (3mg in 100 ml DI)
- DI rinses x3
- Transfer on the target substrate →
- Hot plate @90°C ~30 min
- PMMA removal
 - IFM
 - Sample is soaked in ACE, Then dried with CPD

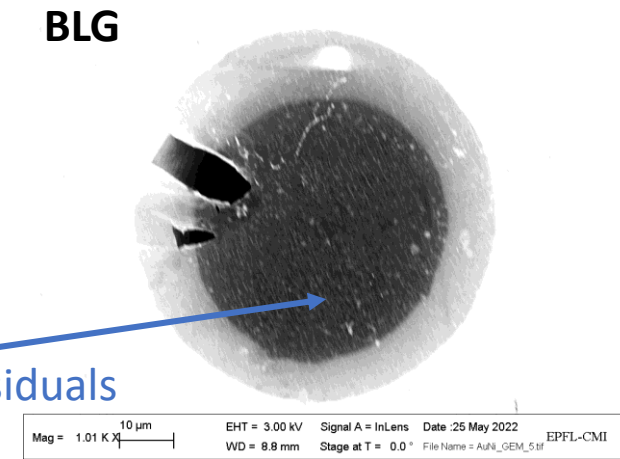
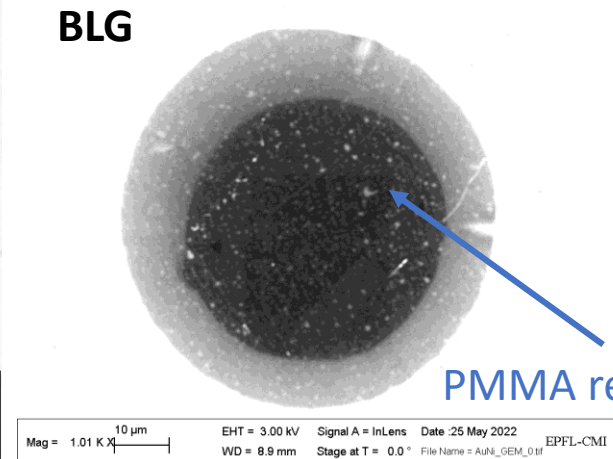
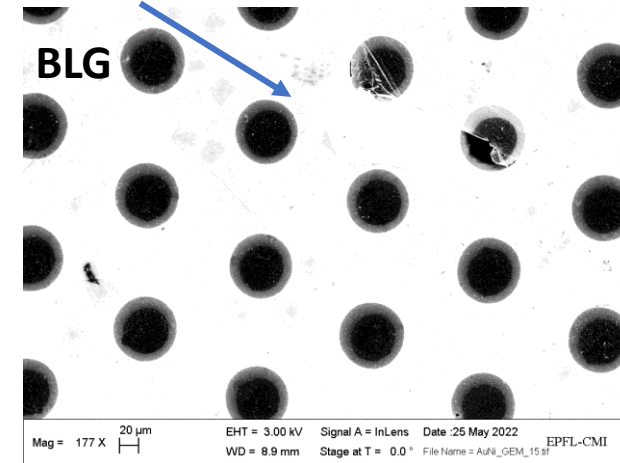
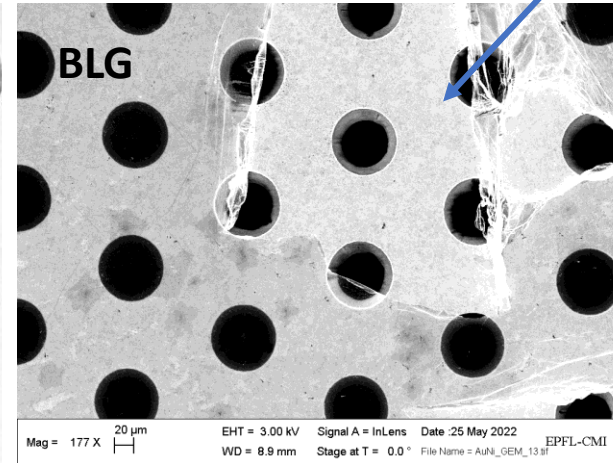
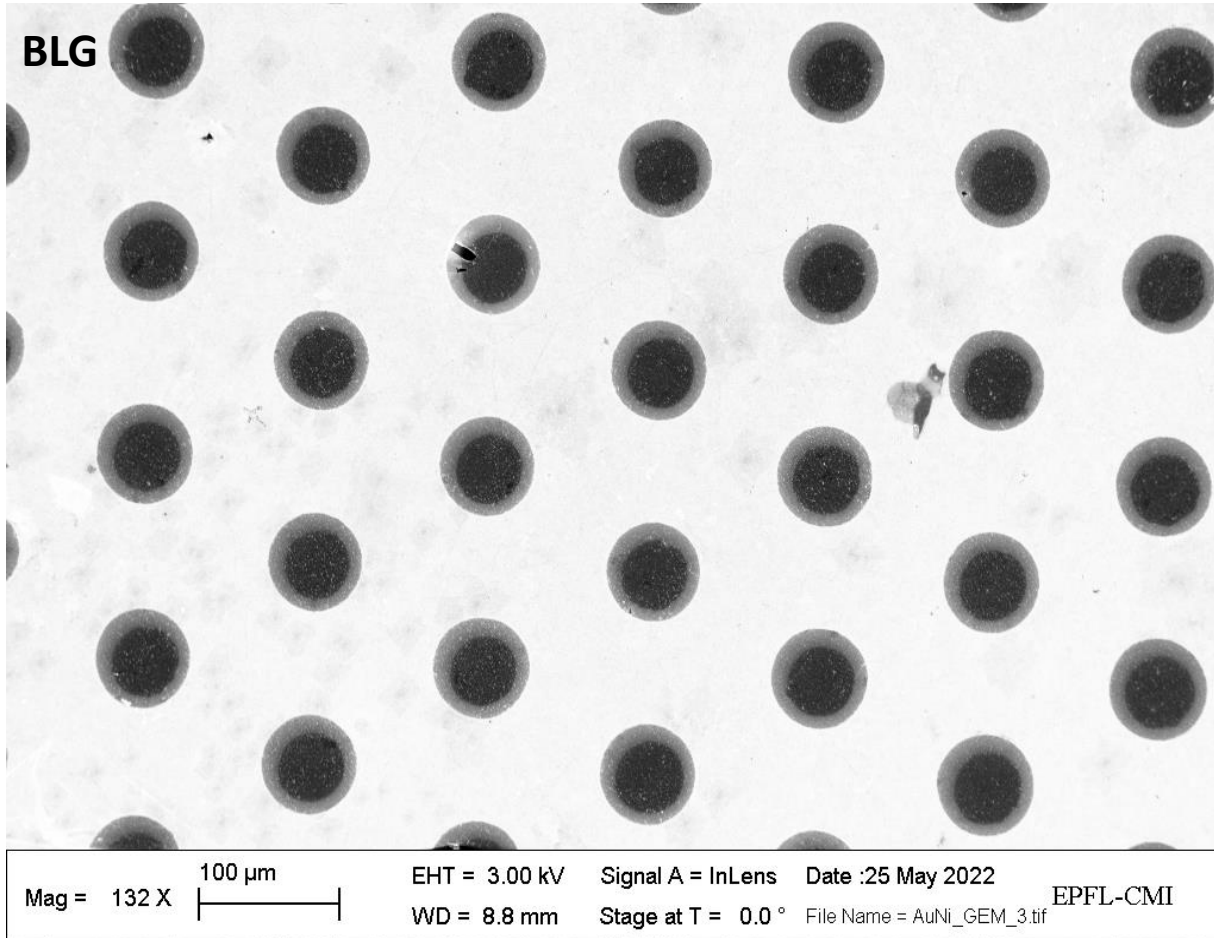
The sample is kept vertically, until water is dried from the holes



- Samples are characterized with SEM

CPD Transfer: BLG on Au GEM 0.5x0.5 cm²

- BLG partially detached and rolled up
- **Good coverage**; most of the holes are covered
- Some of them are completely or partially broken

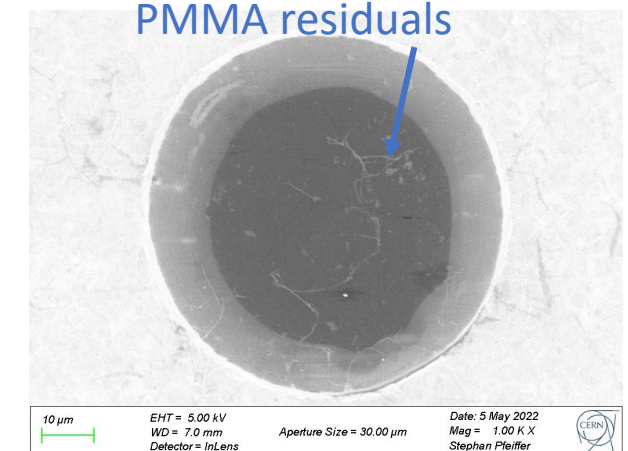
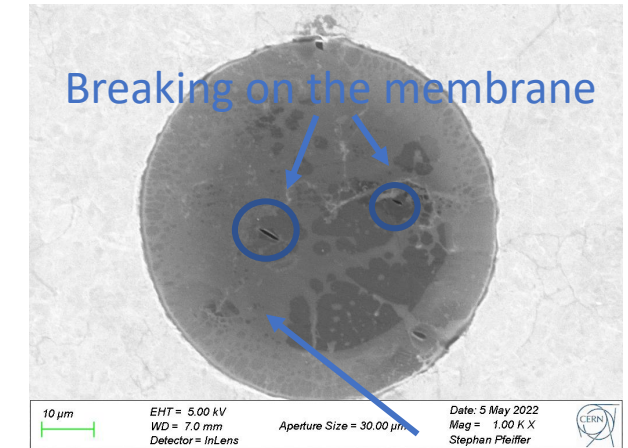
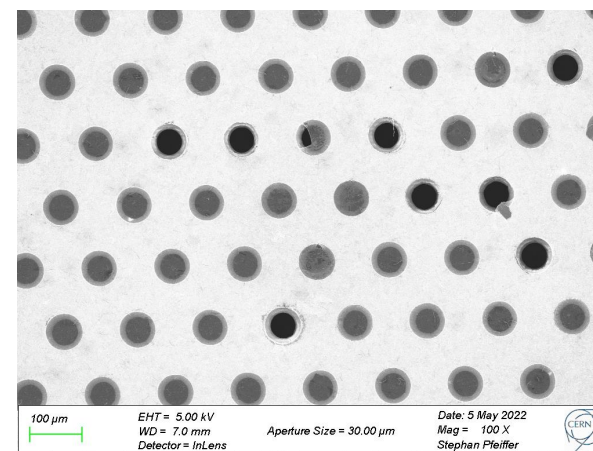
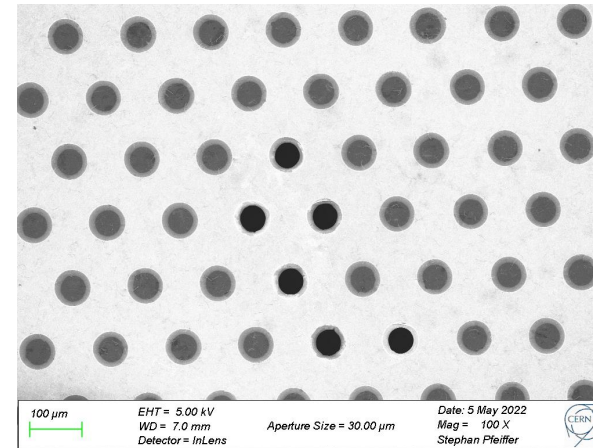
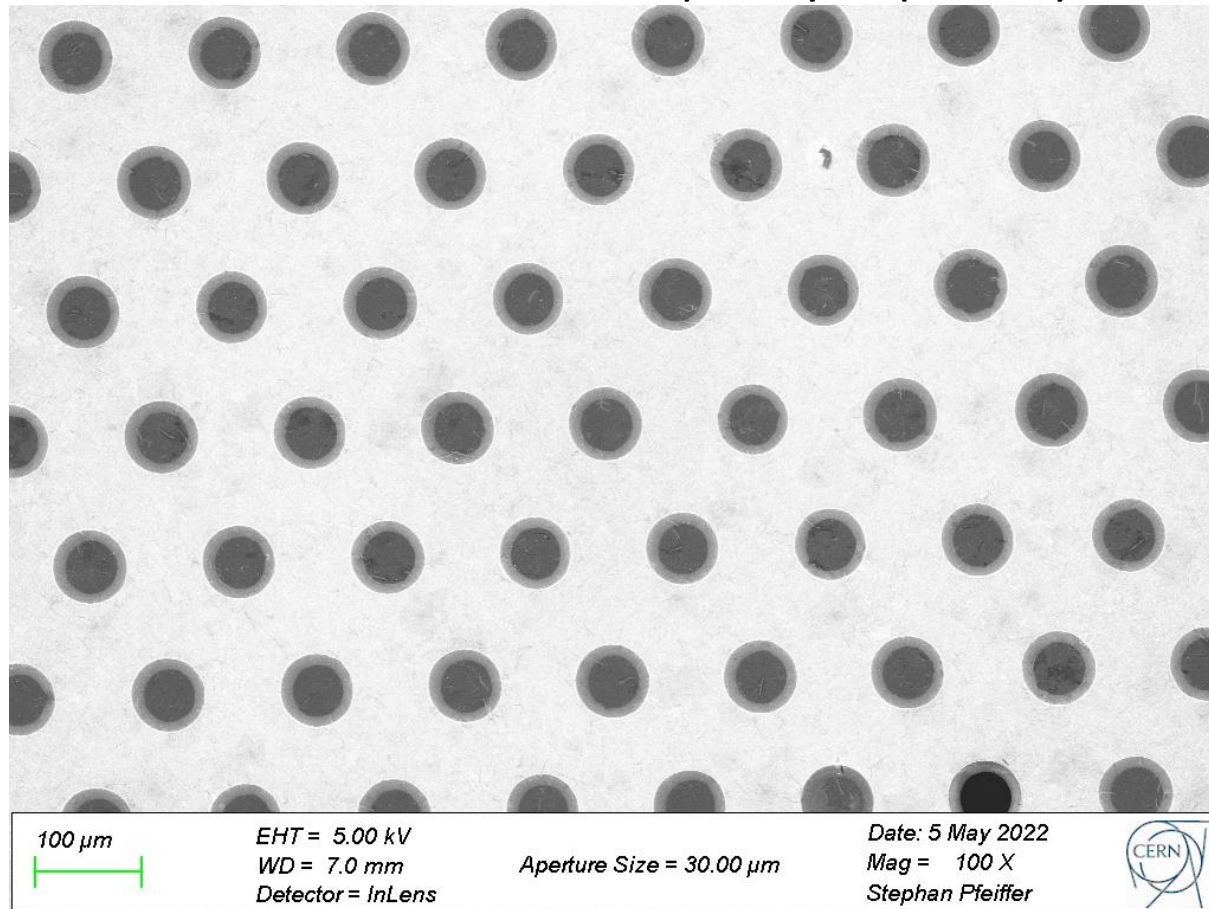


Membrane detachment during the PMMA removal

PMMA residuals

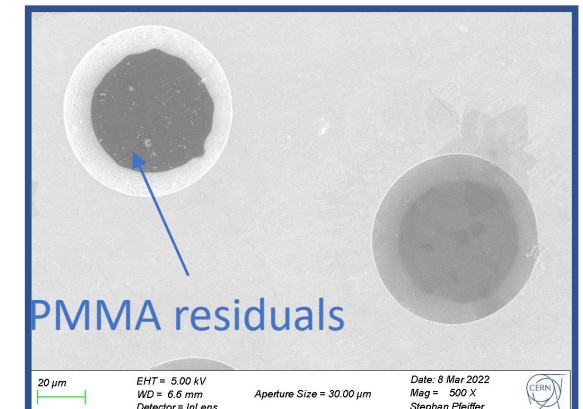
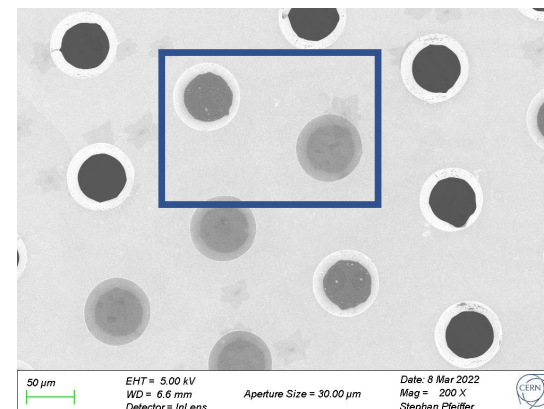
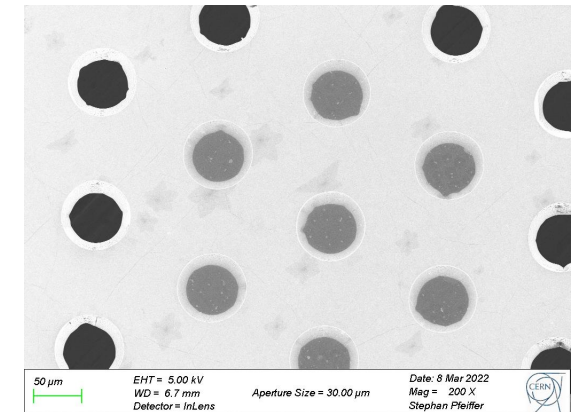
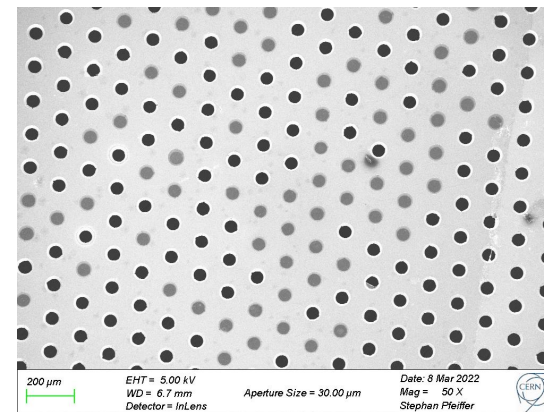
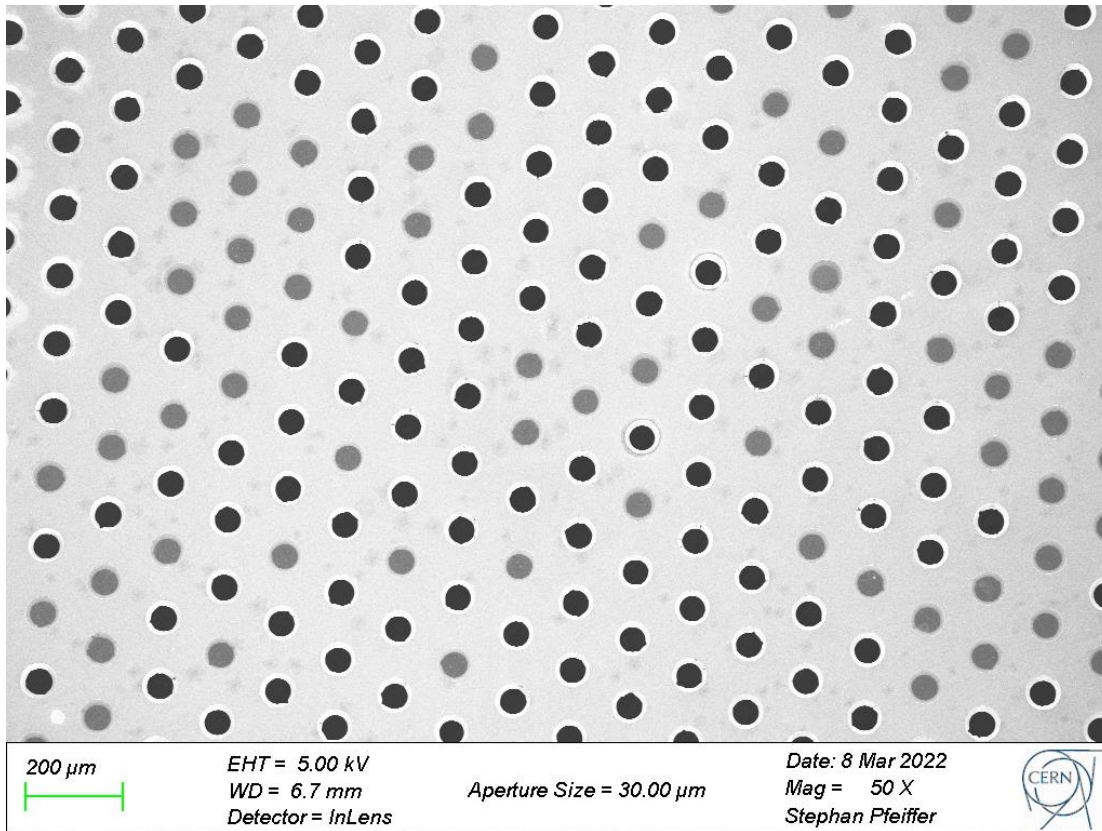
IFM Transfer: BLG on Au GEM 0.5x0.5 cm²

- **BLG** adhesion is okay
- **Good coverage**; most of the holes are covered
- Some of them are completely or partially broken



IFM Transfer: MLG on a Cu GEM piece

- **MLG** adhesion is okay
- **Poor coverage**; most of the holes are uncovered or partially covered
- Some of them are covered



Future Perspective

- The transfer procedure have to be optimized in order to:
- Reach a **full coverage**
- Membrane with **no breakings inside the holes**
- **Lowering PMMA residuals as much as possible** → **PMMA removal** via ACE is not enough:
 - Annealing step would be needed
- Electron transparency measurements in the range of 5-20 eV.
- Gas separation test.

Thank you for your attention!